

WHAT IS CLAIMED IS:

1. An area array semiconductor device comprising:

- a circuit wiring substrate having a circuit wiring;
  - a semiconductor chip mounted on the circuit wiring substrate and electrically connected with the circuit wiring; and
  - a sealing layer composed of a sealing resin;
- wherein the sealing layer is formed such that the sealing layer has an angle of 30 to 60° with respect to a side of the circuit wiring substrate.

2. An area array semiconductor device according to claim 1, wherein the semiconductor chip is mounted on the circuit wiring substrate such that the semiconductor chip has substantially the same angle as an angle which the side of the sealing layer composed of the sealing resin has with respect to the side of the circuit wiring substrate.

3. An electronic circuit board comprising:  
a printed wiring board as a mother board; and  
an area array semiconductor device according to claim 1,

wherein the area array semiconductor device is soldered to the printed wiring board as the mother

board.

4. An electronic circuit board according to claim 3, wherein the area array semiconductor device  
5 is soldered to the printed wiring board with a lead-free solder.